Features:

- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase re-flow solder process.
- Mono-color type.

Descriptions:

- Much smaller than lead frame type components, enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Lightweight for miniature applications.

Applications:

- Model Railroad and Auto Headlights
- Backlighting
- Indicators
- Switch and symbol
- General use

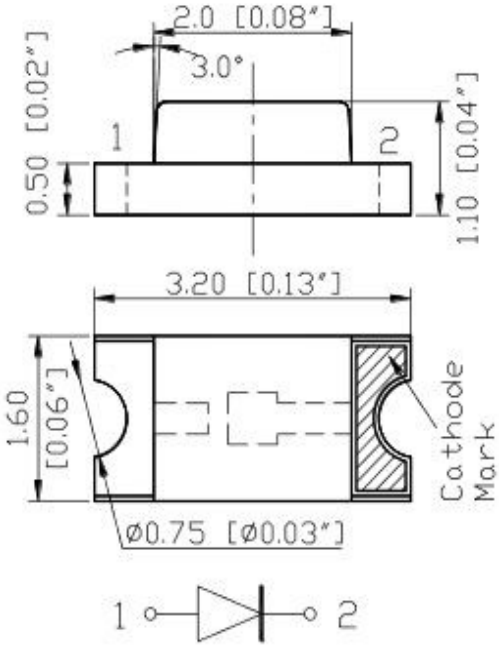
Benefits:

- Low Energy Consumptions
- Low Maintenance Costs
- High Application Design Flexibility
- High Reliability
- Very Competitive prices

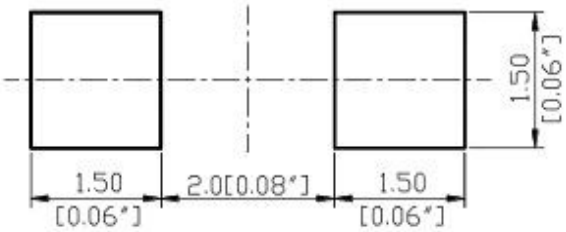
Device material descriptions:

Part ID	Chip		Lens Color
UBSM1206UY21	Material	Emitted Color	Water Clear
	AlInGaP	Super Yellow	

Package Outline Dimensions:



Recommend Pad Layout



Notes: Tolerances Unless Dimensions, 0.1mm
Angles ± 0.5°, Unit: mm

■ Absolute maximum ratings:

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Operating temperature	Topr	-25 ~ +80	°C
Storage Temperature	Tstg	-30 ~ +85	°C
Soldering temperature	Tsol	260 (for 5 Second)	°C
Power Dissipation	Pd	80	mW
Electrostatic Discharge*	ESD	150	V
Peak Forward Current (Duty 1/10 @1KHz)	I_{PF}	100	mA

***Static Electricity Sensitive, care must be fully taken when handling this product.**

■ Electro-Optical characteristics:

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I_V	-----	135	-----	mcd	I_F=20 mA
Viewing angle	2θ 1/2	-----	120	-----	Deg.	I_F=20 mA
Forward Voltage	V_F	-----	2.1	2.4	V	I_F=20 mA
Reverse Current	I_R	-----	-----	50	uA	V_R=5V
Wavelength	λ p	-----	590	-----	nm	I_F=20 mA
	λ d	-----	585~595	-----	nm	

***Visible Light Spectrum:**